

Title (en)

HIGH TEMPERATURE BOLT MATERIAL

Title (de)

HOCHTEMPERATURBOLZENMATERIAL

Title (fr)

MATERIAU DE BOULON HAUTE TEMPERATURE

Publication

**EP 1681359 A1 20060719 (EN)**

Application

**EP 04772713 A 20040827**

Priority

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- JP 2003306103 A 20030829

Abstract (en)

A high temperature bolt material, characterized in that it is a ferrite steel comprising 8 wt % or more of Cr and having a tempered martensite structure and can be used in a high temperature region of higher than 500°C; and a method for producing the high temperature bolt material which comprises subjecting the above-mentioned steel material to a heat treatment comprising a quenching or normalizing at a temperature of 1000°C or higher and then to a tempering at a temperature of 730°C or higher. The above ferrite steel high temperature bolt material is excellent in characteristics of the resistance to stress relaxation.

IPC 1-7

**C21D 9/00; C22C 38/00; C22C 38/18; C22C 38/54; F01D 25/24; F02C 7/00**

IPC 8 full level

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CPC (source: EP US)

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Cited by

CN106555036A; EP3719163A1; EP1988182A4; CN106884074A; EP3719159A1; WO2020200634A1; WO2020200608A1

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